			P		Hi s	Search Text			DBs	Time Stamp	m m en	ro De	
	9		B R S	6	1	(118/52 118/56 118/50 118/320 118/500 42 427/425) and (semiconductor or wafer) and or cap)	7/2 (pl	USP 40 US-F 40 B; EI US JPO; DER T;	PGPI PO;	2002/06/27 16:2		on	0
	10		R	4	- 1	5853803,URPN.		USPA		2002/06/27 15:55		-	
	11		۲	6		"5180431" "5349978" "5351360" "54033 5439519" "5454371").PN.	97'	USPA	т	2002/06/27 15:56		c)
	12	BRS	7	22 78	n 4	118/52 118/56 118/50 118/320 118/500 27/240 427/425) and (semiconductor or wafa 01 ((118/52 118/56 118/50 118/320 118/500 27/240 427/425) and (semiconductor or wafe d (plug or cap))	er)) er)	JPO; DERW	SPU D;	2002/06/27 16:25		0	
1	13	BRSB	1 0 7	6	h(11021/00		T; EPO; J DERW T	PO; EN	2002/06/27 17:07		0	
1	4	1-	5			11021/27		EPO; J DERWI T;	PO; EN	2002/06/27 17:02		0	
15		S	15 08		11: or : 118	98/611 134/902) and (semiconductor or er)) not (((118/52 118/56 118/50 118/32) 15/500 427/424) and (semiconductor vafer)) not ((118/52 118/56 118/50 118/320 (500 427/240 427/425) and (semiconductor rafer) and (plug or cap)))		USPAT, US-PGF B; EPO; JPO; DERWE	νυ 2	2002/06/27 17:07	***************************************	0	
16	:		11 99 1	1		1021/00) and (semiconductor or wafer)	Ε	r; PO; JP DERWE	O; N 2	002/06/27 17:07		0	
17	F	٦ 1		1	1-3	60151	U B Ji	ISPAT; S-PGP(; EPO; PO; ERWEN	20	102/06/27 17:26	C		
18	B R S			ip'	113		US B; JP	SPAT; S-PGPU EPO; O; RWEN	į	02/06/27 17:26	0		
9	BRS	0				D151"	US 3; E IPC DEI	PAT; -PGPU EPO;); RWEN	200	2/06/27 17:26	0		
	R S	13 73	(h (c	ov	110: rer	21/00) and (semiconductor or wafer) and or top)	PC); JPO;	2000	/06/28 08:29	0		